



AI EDGE INFERENCE COMPUTER

RCO-6000-RPL-2N-1E

AI Edge Industrial Computer with LGA 1700 for Intel® Core™ (Series 2)/14th/13th/12th Gen Processors & R680E PCH, 2 Bay U.2 15mm NVMe, 1x PCIe Expansion

Features

- Intel® Core™ Processors (BTL, Series 2) / 14th / 13th / 12th Gen RPL/ADL Series, LGA1700
- Intel® R680E Chipset
- 2x DDR5 4800/5600 MT/s SODIMM. Max. up to 96GB
- 3x Independent Displays: 1x DVI-I, 2x DisplayPort
- 2x Intel® 2.5 GbE supporting Wake-on-LAN and PXE
- 1x PCIe x16 (8-lane) to support dedicated GPU
- 1x Full-size Mini PCIe for communication or expansion modules, 2x SIM socket
- 2x 15mm Hot-swappable NVMe SSD, Support RAID 0, 1
- 1x 9mm 2.5" SATA SSD (Internal), 1x 7mm 2.5" SATA SSD (Hot-swap)
- 1x M.2 (E Key, PCIe x1, USB 2.0, 2230)
- 1x M.2 (B Key, 2242/3042/3052, PCIe x2, Support AI Module/NVMe Storage, PCIe x1 & USB 3.2 Gen1, Support 4G/5G)
- 6x RS-232/422/485 (4x internal), 8x USB 3.2 Gen 2
- 9 to 48VDC Wide Range Power Input Supporting AT/ATX Mode
- Wide Operating Temperature -25°C up to 45°C
- TPM 2.0 Supported



Specifications

System	
Processor	
Standard	
13th Gen Intel® Core™ Processors (Raptor Lake-S)	
- Intel® Core™ i7-13700TE, 35W	
- Intel® Core™ i5-13500TE, 35W	
12th Gen Intel® Core™ Processors (Alder Lake-S)	
- Intel® Core™ i7-12700TE, 35W	
- Intel® Core™ i5-12500TE, 35W	
Project Based	
- Intel® Core™ 3 / 5 / 7 (Series 2, Bartlett Lake-S, 45W)	
- 14th Gen Intel® Core™ i3 / i5 / i7 / i9 (Raptor Lake-S Refresh, 35W~65W)	
- 13th Gen Intel® Core™ i3 / i5 / i7 / i9 (Raptor Lake-S, 35W~65W)	
- 12th Gen Intel® Core™ i3 / i5 / i7 / i9 (Alder Lake-S, 35W~65W)	
System Chipset	Intel® R680E Express Chipset
LAN Chipset	2.5 GbE1: Intel I226, 2.5 GbE2: Intel I226 Support Wake-on-LAN and PXE, Support TSN
Audio Codec	Realtek ALC888S
System Memory	2x 262-Pin DDR5 4800/5600 MT/s SODIMM. Max. up to 96GB (ECC and Non-ECC)
Graphics	Intel® UHD Graphics 770/710
BIOS	AMI 256Mbit SPI BIOS
Watchdog	Software Programmable Supports 1~255 sec. System Reset
AI Accelerator	Supports 3x Hailo-8™ modules
TPM	TPM 2.0
Display	
Display Port	2x DisplayPort 1.4a, Support resolution 5120 x 3200, Up to 7680 x 4320
DVI	1x DVI-I, support resolution 1920 x 1200
Multiple Display	Triple Display
Storage	
M.2	1x M.2 B Key, 2242/3042/3052 (PCIe x2, Support AI Module/NVMe Storage) (PCIe x1 & USB 3.2 Gen1, Support 4G/5G)
mSATA	1x mSATA (Shared by 1x Mini PCI Express)
NVMe	1x Removable Cannister Brick with 2.5" 2 Bay U.2 NVMe SSD (Support H=15mm)
SIM Socket	2x External SIM socket (Mini PCIE/M.2 B Key attached)
SSD/HDD	1x 9mm 2.5" SATA HDD Bay (Internal) 1x 7mm 2.5" SATA HDD Bay (Hot-swappable) 2x 15mm 2.5" NVMe SSD Bay (Hot-swappable) Support RAID 0, 1
Expansion	
M.2	1x M.2 (E Key, PCIe x1, USB 2.0, 2230)
Mini PCIe	1x Full-size Mini PCIe (1x shared by 1x mSATA)
PCIe	1x PCIe x16 (8-lane, Gen 3) 1x PCIe x4 (1-lane, Gen 3)
Expansion Modules	
2x EDGEBoost I/O Brackets:	
• 4-port GbE module with Intel® I350 Chipset, RJ-45/M12 connector (PoE optional)	
• 2-Port RJ45 10GbE with Intel X710 Chipset	
• 4-Port USB 3.0 (share PCIe Gen2 x1 bandwidth)	
• 1x M.2 B-Key, 2242 for AI/NVMe, 1x M.2 B-Key, 3042/3052 for 5G/AI/NVMe	
• 1x M.2 M-Key, PCIe x4 Lane, 2242/2260 for AI Module/NVMe	
• 1x M.2 for 5G (B Key, PCIe x1, USB 3.0, 3042/3052), 2x SIM socket, 1x SIM switch	
• 1x RJ45 port for OOB Management Module	
I/O	
Audio	1x Mic-in, 1x Line-out

CAN	2x CAN 2.0 A/B 2-pin Internal header
COM	2x RS-232/422/485 ; 4x RS-232/422/485 (Internal)
DIO	8 in / 8 out (Isolated)
EDGEBoost I/O Bracket	2x EDGEBoost I/O Bracket (By mini PCIe interface)
LAN	2x RJ45
USB	8x USB 3.2 Gen 2 (10 Gbps) 1x USB 2.0 (Internal)
Others	5x WiFi Antenna Holes 1x Power Switch, 1x AT/ATX Switch, 1x Remote Power On/Off 1x PC/Car Mode Switch, 1x Delay Time Switch 1x Removable CMOS Battery

Operating System	
Windows	Windows 10/11
Linux	Linux kernel

Power	
Power Adapter	Optional AC/DC 24V/11.67A, 280W Optional AC/DC 24V/15A, 360W (i9 CPU/GPU/Card Expansion)
Power Mode	AT, ATX
Power Ignition Sensing	Power Ignition Management
Power Supply Voltage	9~48VDC 12~48VDC for NVMe/GPU EDGEboost Node
Power Connector	5-pin Terminal Block 4-pin Terminal Block for GPU and NVMe EDGEBoost Node (12V requires 4-pin terminal block)
Power Protection	OVP (Over Voltage Protection) OCP (Over Current Protection) Reverse Protection

Environment	
Operating Temperature	-25°C to 45°C (35W~65W CPU, with GPU)
Storage Temperature	-30°C to 85°C
Relative Humidity	10% to 95% (non-condensing)
Certification	UL 62368 Ed. 3, CE, FCC Class A
Vibration	With HDD: 1 Grms (5 - 500 Hz, 0.5 hr/axis) With SSD: 3 Grms (5 - 500 Hz, 0.5 hr/axis)
Shock	With SSD: 20G half-sin 11ms

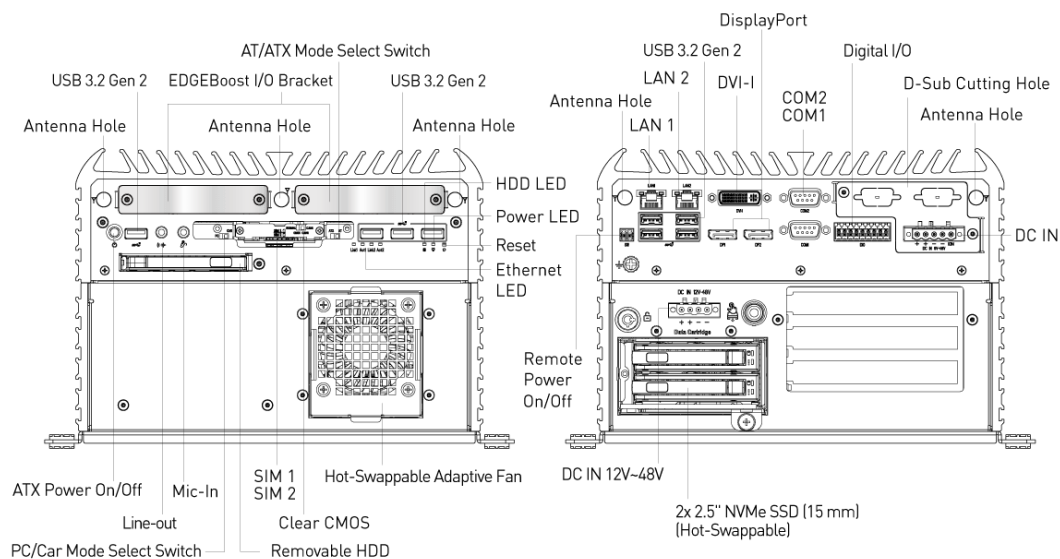
Physical	
Dimensions	240 (W) x 261 (D) x 166.9 (H) mm
Weights	11 ~ 12 kg
Construction	Extruded Aluminum with Heavy Duty Metal
Mounting Options	Wall Mounting

* Processor Base Power: 35W, 45W, 60W, 65W (CPU-dependent); View appendix for complete supported processors table.

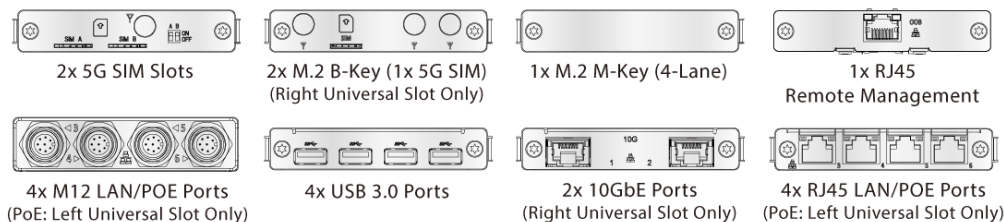
** 65W CPUS may experience thermal throttling depending on extreme application workloads; this is also due to an increase in the physical CPU cores from the Intel silicon (up to 24 cores). Please note, this does not indicate system malfunction or problems in the fanless design. Please consult our embedded engineers for the best configuration to match your application requirements.

*** All specifications and photos are subject to change without notice.

External I/O Mechanical Layout

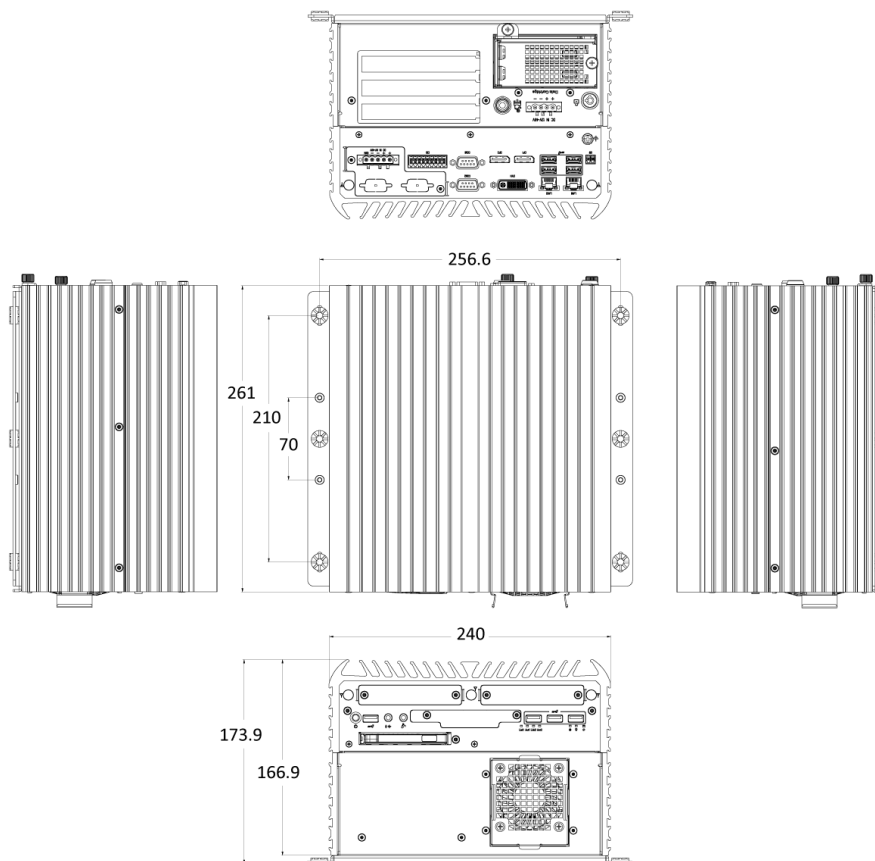


Available EDGEBoost I/O



Dimension

Unit: mm



Compatible CPU Support List

Generation and Code Name	Processor	P + E Cores	P-core Base Frequency	L3 Cache	Base Power
Intel® Core™ Series 2 Bartlett Lake-S	Intel® Core™ 7 Processor 251TE	8P + 16E	1.4 GHz	36 MB	45W
	Intel® Core™ 5 Processor 221TE	6P + 8E	1.8 GHz	24 MB	45W
	Intel® Core™ 3 Processor 201TE	4P	2.9 GHz	12 MB	45W
14th Gen Raptor Lake-S Refresh	Intel® Core™ i9 processor 14900	8P + 16E	2 GHz	36 MB	65W
	Intel® Core™ i9 processor 14900T	8P + 16E	1.1 GHz	36 MB	35W
	Intel® Core™ i7 processor 14700	8P + 12E	2.1 GHz	33 MB	65W
	Intel® Core™ i7 processor 14700T	8P + 12E	1.3 GHz	33 MB	35W
	Intel® Core™ i5 processor 14500	6P + 8E	2.6 GHz	24 MB	65W
	Intel® Core™ i5 processor 14500T	6P + 8E	1.7 GHz	24 MB	35W
	Intel® Core™ i3 processor 14100	4P	3.5 GHz	12 MB	60W
	Intel® Core™ i3 processor 14100T	4P	2.7 GHz	12 MB	35W
13th Gen Raptor Lake-S	Intel® Core™ i9 processor 13900E	8P + 16E	1.80 GHz	36 MB	65W
	Intel® Core™ i9 processor 13900TE	8P + 16E	1.00 GHz	36 MB	35W
	Intel® Core™ i7 processor 13700E	8P + 8E	1.90 GHz	30 MB	65W
	Intel® Core™ i7 processor 13700TE	8P + 8E	1.10 GHz	30 MB	35W
	Intel® Core™ i5 processor 13500E	6P + 8E	2.40 GHz	24 MB	65W
	Intel® Core™ i5 processor 13500TE	6P + 8E	1.30 GHz	24 MB	35W
	Intel® Core™ i3 processor 13100E	4P	3.30 GHz	12 MB	60W
	Intel® Core™ i3 processor 13100TE	4P	2.40 GHz	12 MB	35W
12th Gen Alder Lake-S	Intel® Core™ i9 processor 12900E	8P + 8E	2.30 GHz	30 MB	65W
	Intel® Core™ i9 processor 12900TE	8P + 8E	1.10 GHz	30 MB	35W
	Intel® Core™ i7 processor 12700E	8P + 4E	2.10 GHz	25 MB	65W
	Intel® Core™ i7 processor 12700TE	8P + 4E	1.40 GHz	25 MB	35W
	Intel® Core™ i5 processor 12500E	6P	2.90 GHz	18 MB	65W
	Intel® Core™ i5 processor 12500TE	6P	1.90 GHz	18 MB	35W
	Intel® Core™ i3 processor 12100E	4P	3.20 GHz	12 MB	60W
	Intel® Core™ i3 processor 12100TE	4P	2.10 GHz	12 MB	35W

Compatible GPU AVL

Model	GPU Memory	Memory Bandwidth	CUDA Cores	Tensor Cores	RT Cores	AI TOPS	Dimensions	Power & Thermal
NVIDIA RTX PRO 4000 Blackwell SFF Edition	24GB GDDR7 ECC	432 GB/s	8,960	280	70	770	2.7" H x 6.6" HHHL, Dual Slot	70 W
NVIDIA RTX PRO 2000 Blackwell	16GB GDDR7 ECC	288 GB/s	4,352	136	34	545	2.7" H x 6.6" L, HHHL Dual Slot	70 W
RTX 4000 SFF Ada Generation	20GB GDDR6 ECC	320 GB/s	6144	192	48	307	4.7" x 6.6" LP DS	70 W
NVIDIA RTX 2000 Ada Generation	16 GB GDDR6 with ECC	224 GB/s	2816	88	22	192	2.7" x 6.6" LP DS	70 W
NVIDIA RTX A1000	8GB GDDR6	192 GB/s	2304	72	18	108	2.7" H x 6.4" LP SS	50 W

Compliances and Standards

Vibration	With HDD: 1 Grms (5 - 500 Hz, 0.5 hr/axis) With SSD: 3 Grms (5 - 500 Hz, 0.5 hr/axis) IEC60068-2-64:2008 Designed to comply with MIL-STD-810H Method 514.8 Procedure I
Shock	With SSD: 20G half-sin 11ms IEC60068-2-27:2008 Designed to comply with MIL-STD-810H Method 516.8 Procedure I
Operating Temperature	-25°C to 45°C (35W~65W CPU, with GPU) IEC60068-2-1:2007 (Cold test procedure) IEC60068-2-2:2007 (Dry heat test procedure) IEC60068-2-3:2007 (Damp heat, steady state, test procedure) IEC60068-2-14:2009 (Wide temperature range thermal shock)
EMC	- FCC Class A - CE - ICES-003 - UKCA - Industrial EMC Compliance - EN 61000-4-2: 2009 - EN IEC 61000-4-3: 2020 - EN 61000-4-4: 2012 - EN 61000-4-5: 2014 +A1: 2017 - EN 61000-4-6: 2014
Safety	- UL Safety: UL62368-1, 3rd Ed., (cULus) - Test procedure: CB Scheme - Standard: IEC 62368-1:2018

Available Models

Model No.	Description
RCO-6000-RPL-2N-P	AI Edge Inference Computer with LGA 1700 for Intel® Core™ (Series 2)/14th/13th/12th Gen Processors & R680E PCH, 2 Bay U.2 15mm NVMe, 1x PCIe Expansion

Optional Accessories

Model No.	Description
1-E09A28001	Adapter AC/DC 24V/11.67A 280W with 5pin Terminal Block Plug 5.0mm Pitch
1-E09A36003	Adapter AC/DC 48V/7.5A 360W with 5pin Terminal Block Plug 5.0mm Pitch
999930	Power Cord, 3-pin US Type, 180cm
1-TPCD00002	Power Cord, European Type, 180cm
1-TPCD00001	Power Cord, 3-pin UK Type, 180cm

Packing List

1x RCO-6000-RPL Series AI Edge Inference Computer
 1x Wall Mount Kit
 1x Accessory Kit
 1x DVI to VGA Adapter

Exports And Tariff Codes

ECCN	5A992.c
HTS	8471.50.0150
ScheduleB	84.71

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